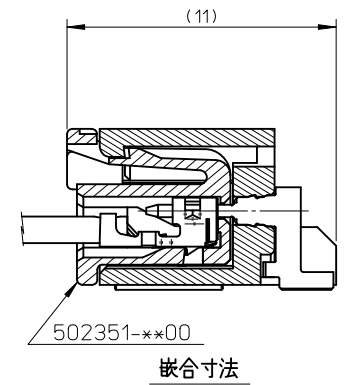
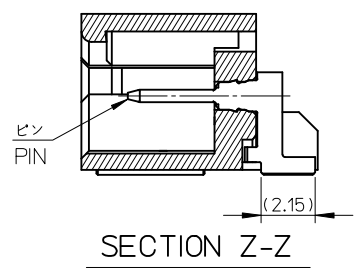
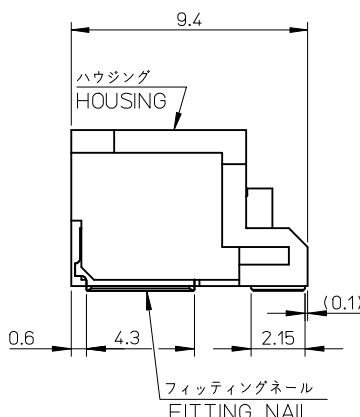
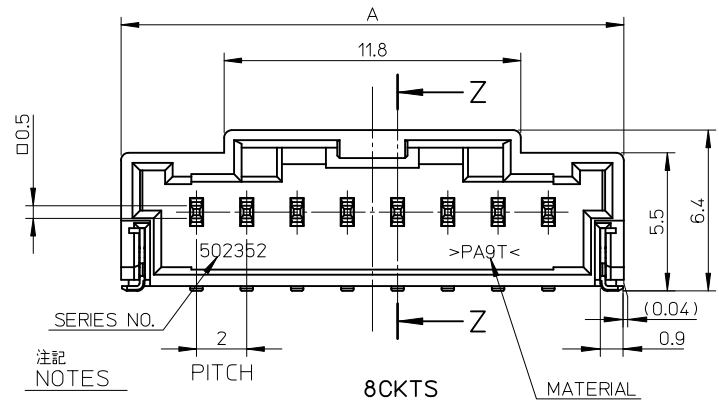


参考基板取り付け寸法(N=極数)



- 注記 NOTES
- 材質
ハウジング: 耐熱性ナイロン
ピン: 銅合金、ニッケル下地、錫メッキ、金メッキ
フィッティングネール: 銅合金、ニッケル下地、錫メッキ
MATERIAL
HOUSING: POLYAMIDE
PIN: COPPER ALLOY, GOLD OR TIN OVER NICKEL PLATE.
FITTING NAIL: COPPER ALLOY, TIN OVER NICKEL PLATE.
 - 色: ナチュラル
COLOR: NATURAL
 - 嵌合相手
ハウジング: 502351-**00
錫メッキ端子: 50212-8*00, 50372-8*00
金メッキ端子: 56161-8*81
MATES WITH
HOUSING: 502351-**00
SN PLATING TERMINAL: 50212-8*00, 50372-8*00
AU PLATING TERMINAL: 56161-8*81
 - エンボス梱包品の詳細はSD-502352-002参照
DETAILED TAPING PACKAGE, SEE SD-502352-002.
 - ELV及びRoHS適合
ELV AND RoHS COMPLIANT

Au	20.0	502352-0818	8
	18.0	502352-0718	7
	16.0	502352-0618	6
	14.0	502352-0518	5
	12.0	502352-0418	4
	10.0	502352-0318	3
	8.0	502352-0218	2
PLATING	A	MATERIAL NO.	CKTS

Sn	20.0	502352-0808	8
	18.0	502352-0708	7
	16.0	502352-0608	6
	14.0	502352-0508	5
	12.0	502352-0408	4
	10.0	502352-0308	3
	8.0	502352-0208	2
PLATING	A	MATERIAL NO.	CKTS

REVISED EC NO: JTR2012-0086 DRWN: Y.TAMAKI 2012/02/12 CHKD: H.KOMATSU 2012/03/12 APPR: M.YAMAMOTO 2012/03/14	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE 5:1	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION
	10 UNDER	±0.2	DRAWN BY SHSHIBATA	DATE 2007/12/18	TITLE 2.0MM PITCH W/B CONN. WAFER ASSY R/A SMT		
	10 OVER 30 UNDER	±0.25	CHECKED BY HKOMATSU	DATE 2007/12/18	MOLEX INCORPORATED		
	30 OVER	±0.3	APPROVED BY AKANESHIGE	DATE 2007/12/18	DOCUMENT NO. SD-502352-001	SHEET NO. 1 OF 2	
REV	DESCRIPTION	ANGULAR ±3°	MATERIAL NO. SEE CHART		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION		
DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS							

10 9 8 7 6 5 4 3 2 1

F

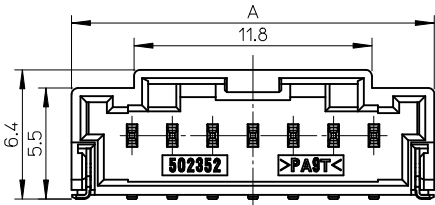
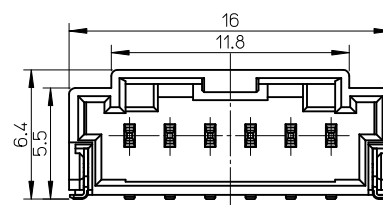
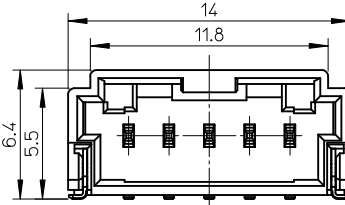
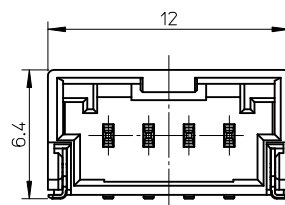
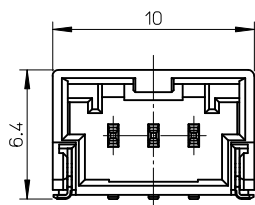
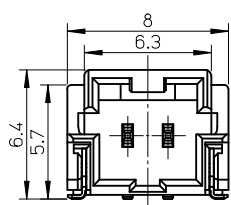
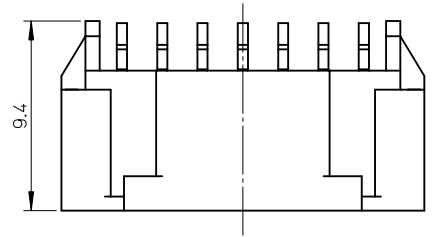
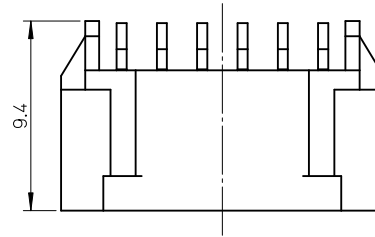
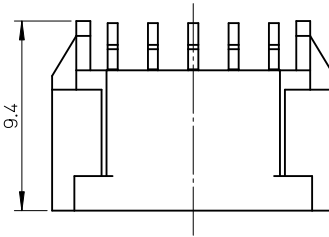
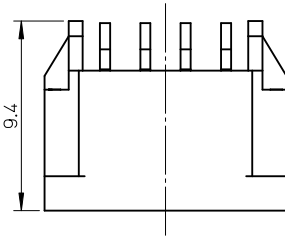
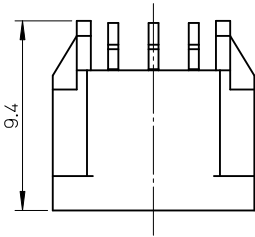
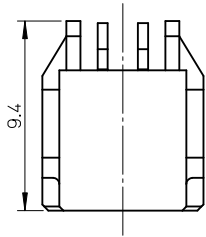
E

D

C

B

A



2CKTS

3CKTS

4CKTS

5CKTS

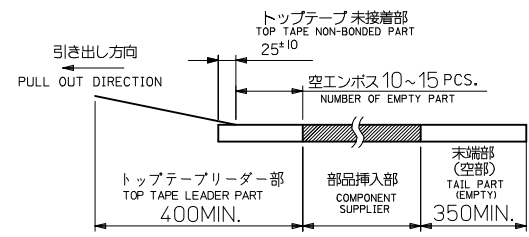
6CKTS

7CKTS or MORE

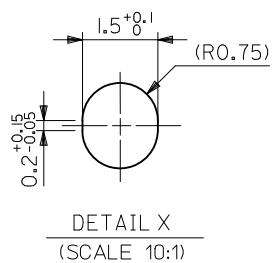
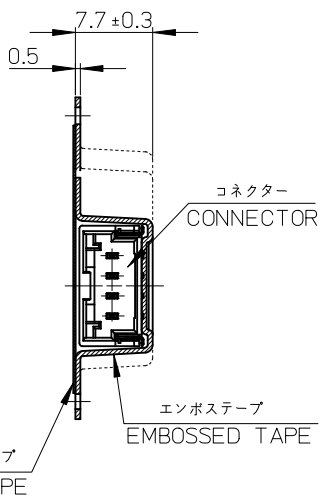
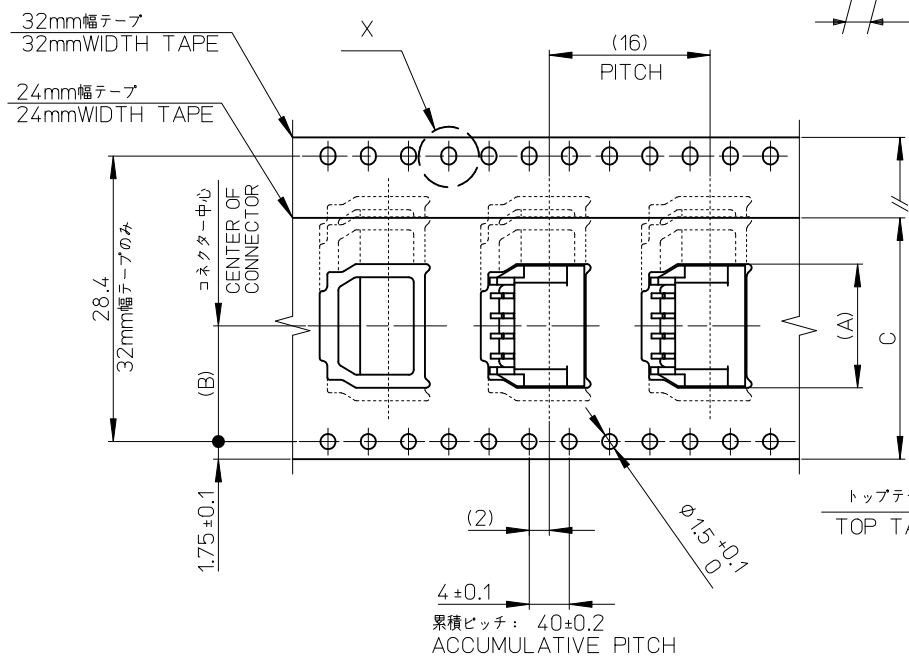
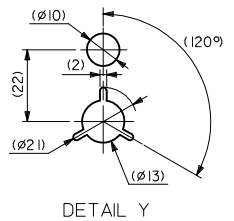
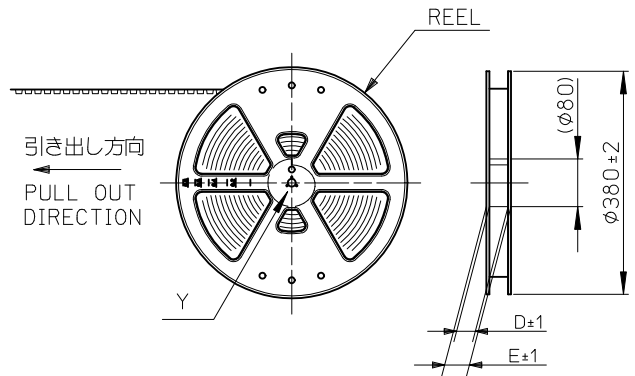
REVISED EC NO: JTR2012-0086 DRWN: Y. TAKAKI 2012/02/22 CHK'D: H. KOMATSU 2012/03/12 APPR: M. YAMAMOTO 2012/03/14	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY	SCALE 4:1	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION
	10 UNDER	± 0.2	DRAWN BY SHSHIBATA	DATE 2007/12/18	TITLE 2.0MM PITCH W/B CONN. WAFER ASSY R/A SMT	
	10 OVER 30 UNDER	± 0.25	CHECKED BY HKOMATSU	DATE 2007/12/18		
	30 OVER	± 0.3	APPROVED BY AKANESHIGE	DATE 2007/12/18	MOLEX INCORPORATED	
ANGULAR ± 3 °		MATERIAL NO.	SEE CHART	DOCUMENT NO. SD-502352-001		
DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		SIZE A3	THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION			

注記
NOTES

- 製品番号502352-***0 詳細寸法については、製品単体図面を参照下さい。
PART NO. 502352-***0 . SEE SALES DRAWING FOR CONNECTOR
- 梱包数量： 700個/リール
NUMBER OF CONNECTORS 700PCS/REEL
- リードテープ長さ
LEAD TAPE LENGHT



4. 材料
MATERIAL
キャリアテープ： ポリスチレン
CARRIER TAPE: POLYSTYRENE
トップテープ： PET, PE, PEF
TOP TAPE
リール： ポリスチレン
REEL: POLYSTYRENE



引き出し方向
PULL OUT DIRECTION

エンボステープ内の製品の向き
DIRECTION OF CONNECTOR
IN EMBOSSED TAPE

REVISED EC NO: JTR2012-0086 DRWN:YTAMAKI 2012/03/12 CHKD:HKOMATSU 2012/03/12 APPR: MAYAMAMOTO 2012/03/14	DESCRIPTION	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE	DESIGN UNITS	THIRD ANGLE PROJECTION	
		10 UNDER	±0.2	DRAWN BY	DATE	TITLE	2.0MM PITCH W/B CONN. WAFFER ASSY EMBOSSED TAPE PACKAGE		
		10 OVER 30 UNDER	±0.25	SHSHIBATA	2007/6/6	MOLEX MOLEX INCORPORATED			
		30 OVER	±0.3	TAITO	2007/6/6		DOCUMENT NO.	SHEET NO.	
ANGULAR	±1 °	DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		APPROVED BY MAYAMAMOTO 2012/03/14		SEE CHART		SD-502352-002	1 OF 2
REV				SIZE A3	THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION				

